WAFER PROBE CARD SOLUTIONS



Vertical Probe Card ViProbe® and ViProbe®II - From the Established Solution to the Next Generation

For years, the FEINMETALL ViProbe® has dominated the vertical probe card industry. Several advantages such as the stable contact performance as well as the simple exchange of the contact elements and outstanding temperature behavior make this probing solution the favorite to the automotive industry.

With the introduction of the next generation of vertical wafer probing, the ViProbe®II, all these advantages are extended by multiple lifetime extension options and further security additions to ensure security of the DUT.

Advantages

- Accurate wafer probing on fine-pitch pads over the whole temperature range
- Simple exchange of single contact elements, complete replacement of the probes and even probe heads by the customer leads to lowest cost-of-ownership
- Adjustable to most applications: from high pin count, to copper probing up to fine-pitch
- Multiple lifetime extension
- Extended security features of the probe head

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Min pitch of the DUT
Diameter of the contact element
Max active area
Capable temperature range
Current carrying capability at RT
Contact force at rec. OD

ViProbe®

Down to 56 µm

Down to 1.6 mil

Up to 80 mm x 80 mm

From -55°C to 180°C

Up to 800 mA

From 2.6 cN to 10.8 cN

ViProbe[®]II

Down to 40 μm
Down to 1.1 mil
Up to 105 mm x 105 mm
From -55°C to 180°C
Up to 800 mA
From 2.2 cN to 10.8 cN